

1. SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:

84136	01	R	X
┆	┆	┆	┆
┆	┆	┆	┆
┆	┆	┆	┆
┆	┆	┆	┆
Drawing number	Device type (1.2.1)	Case outline (1.2.2)	Lead finish per MIL-M-38510

1.2.1 Device type. The device type shall identify the circuit function as follows:

Device type	Generic number	Circuit
01	54ALS273	Octal D-type flip-flops with clear

1.2.2 Case outline. The case outline shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter	Case outline
R	D-8 (20-lead, 1.060" x .310" x .200"), dual-in-line package
S	F-9 (20-lead, .540" x .300" x .100"), flat package
2	C-2 (20-terminal, .358" x .358" x .100"), square chip carrier package

1.3 Absolute maximum ratings.

Supply voltage range - - - - -	-0.5 V dc minimum to +7.0 V dc maximum
Input voltage range- - - - -	-1.5 V dc at -18 mA to +7.0 V dc
Storage temperature- - - - -	-65°C to +150°C
Maximum power dissipation (P_D)	
per flip-flop 1/ - - - - -	159.5 mW
Lead temperature (soldering, 10 seconds) - -	+300°C
Thermal resistance, junction-to-case (θ_{JC}) -	See MIL-M-38510, appendix C
Junction temperature (T_J)- - - - -	+175°C

1.4 Recommended operating conditions.

Supply voltage (V_{CC}) - - - - -	4.5 V dc minimum to 5.5 V dc maximum
Minimum high level input voltage (V_{IH}) - - -	2.0 V dc
Maximum low level input voltage (V_{IL}):	
$V_{IL} = +125^\circ\text{C}$ - - - - -	0.7 V dc
$V_{IL} = +25^\circ\text{C}$ - - - - -	0.8 V dc
$V_{IL} = -55^\circ\text{C}$ - - - - -	0.8 V dc
Case operating temperature range (T_C)- - -	-55°C to +125°C

1/ Maximum power dissipation is defined as $V_{CC} * I_{CC}$, and must withstand the added P_D due to short circuit test; e.g., I_O .

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Width of clear pulse low (t_w CLR) - - - - -	10 ns minimum
Width of clock pulse high or low (t_w CLK) - - - - -	16.5 ns minimum
Data setup time before CLK (t_s CLK) - - - - -	10 ns minimum
Clear inactive state setup time before CLK (t_s CLR) - - - - -	15 ns minimum
Data hold time after CLK (t_h) - - - - -	0 ns minimum

2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Truth table. The truth table shall be as specified on figure 2.

3.2.3 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.4 Switching circuit and waveforms. The switching circuit and waveforms shall be as specified on figure 4.

3.2.5 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full case operating temperature range.

3.4 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in 6.4 herein.

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3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).

3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).

(2) $T_A = +125^{\circ}\text{C}$, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.

c. Subgroup 7 and 8 tests shall verify the truth table as specified in figure 2 herein.

4.3.2 Groups C and D inspections.

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test conditions, method 1005 of MIL-STD-883.

(1) Test condition A, or D using the circuit submitted with the certificate of compliance (see 3.5 herein).

(2) $T_A = +125^{\circ}\text{C}$, minimum.

(3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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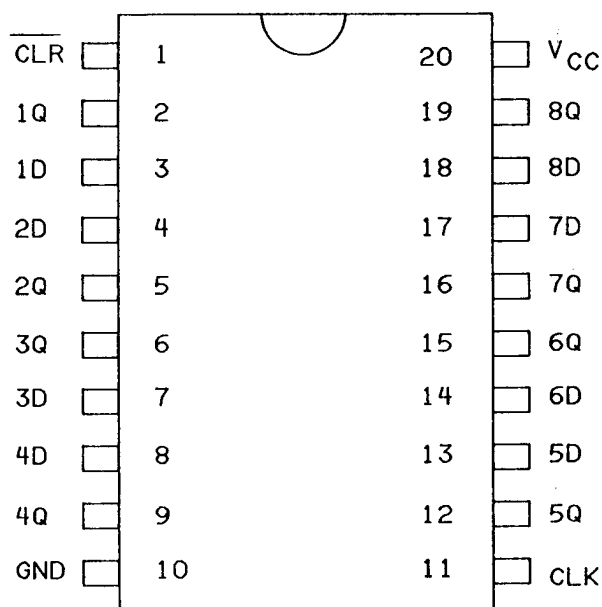
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Cases R and S



Case 2

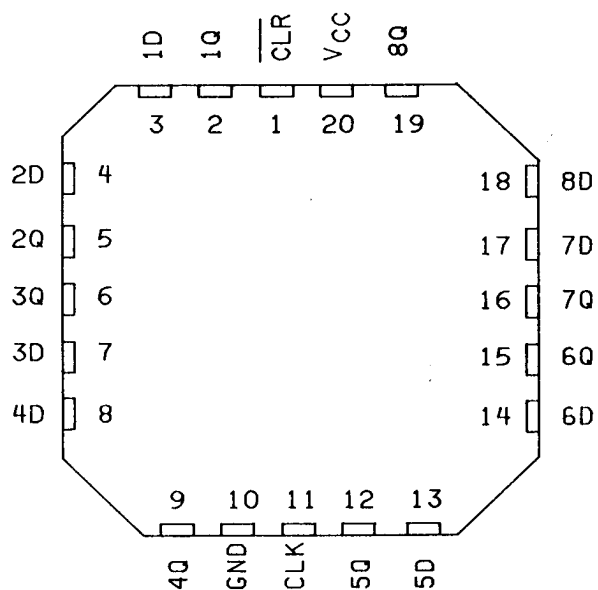


FIGURE 1. Terminal connections (top view).

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Inputs			Output
$\overline{\text{CLR}}$	CLK	D	Q
L	X	X	L
H	↑	H	H
H	↑	L	L
H	L	X	Q_0

H = high voltage level
 L = low voltage level
 X = irrelevant
 Q_0 = level of Q before the indicated steady state
 input conditions were established.
 ↑ = transition from low to high

FIGURE 2. Truth table (each flip-flop).

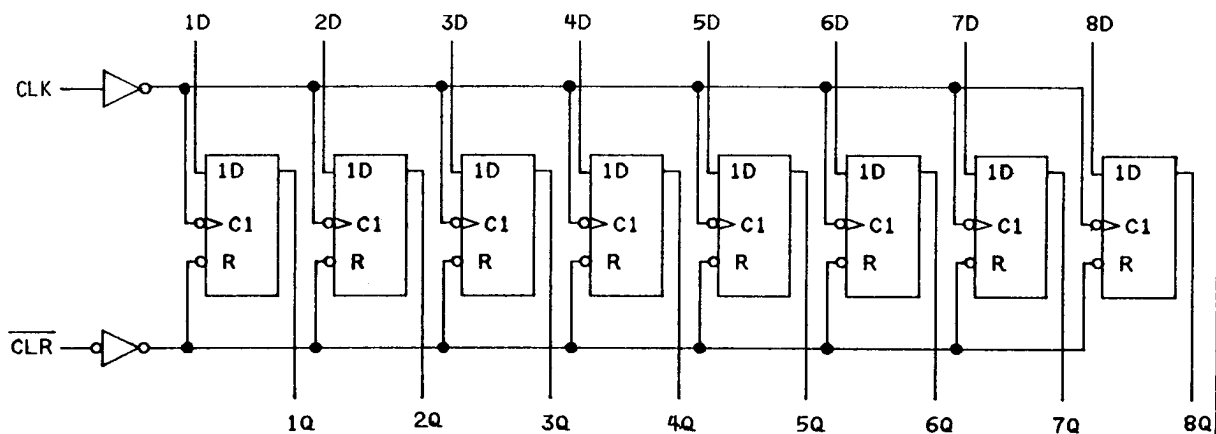


FIGURE 3. Logic diagram.

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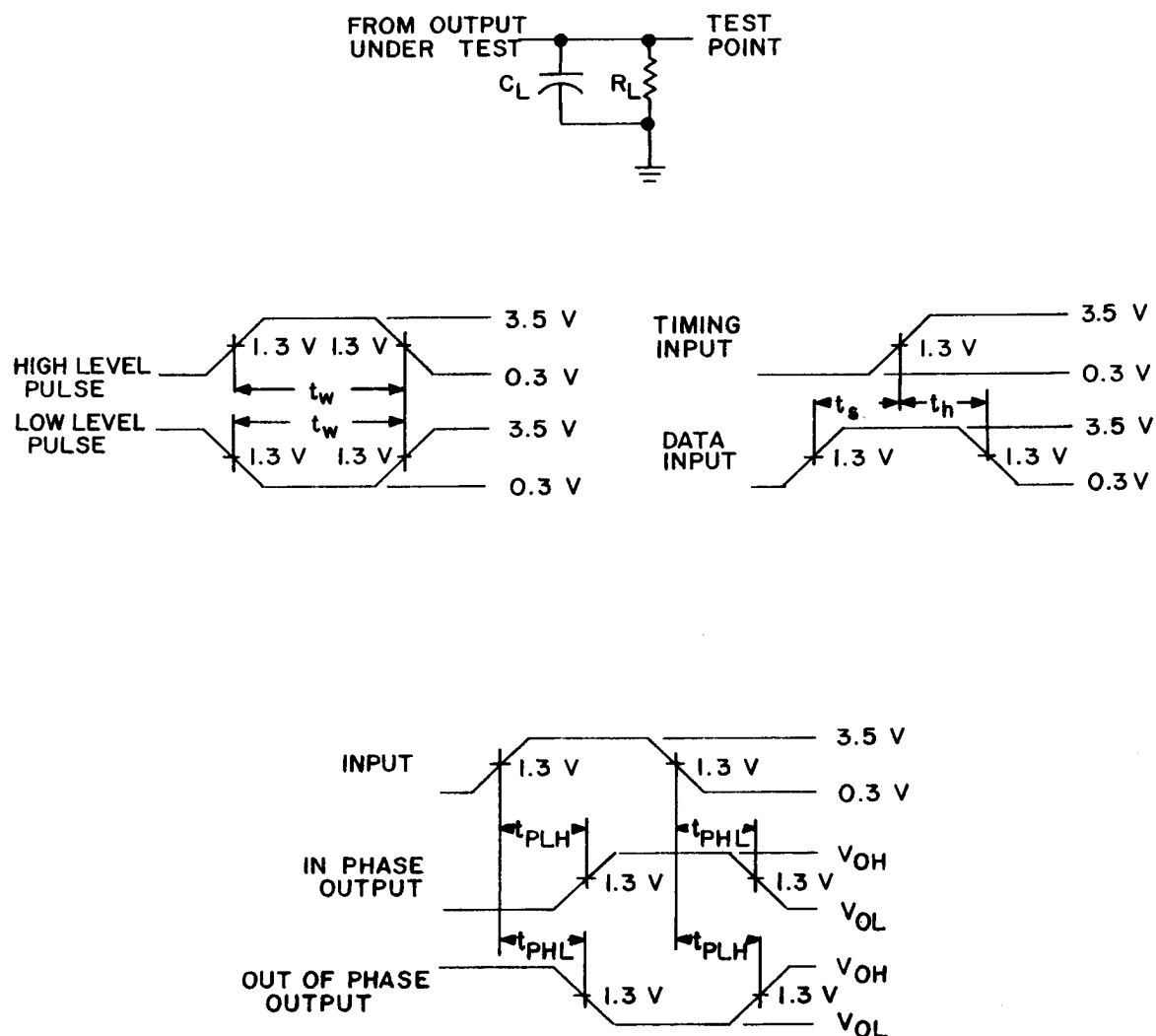
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NOTES:

1. C_L includes probe and jig capacitance.
2. All input pulses have the following characteristics: $PRR \leq 10$ MHz, duty cycle = 50%, $t_r = t_f = 3$ ns ± 1 ns.
3. The outputs are measured one at a time with one input transition per measurement.

FIGURE 4. Switching circuit and waveforms.

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TABLE 1. Electrical performance characteristics.

Test	Symbol	Conditions 1/ -55°C < T _C < +125°C unless otherwise specified	Group A subgroups	Min		Unit
					Max	
High level output voltage	V _{OH}	V _{CC} = 4.5 V V _{IH} = 2.0 V V _{IL} : ② +125°C = 0.7 V ② +25°C = 0.8 V ② -55°C = 0.8 V	1,2,3	2.5		V
		I _{OH} = -0.4 V I _{OH} = -1.0 mA		2.4		
Low level output voltage	V _{OL}	I _{OL} = 12 mA V _{CC} = 4.5 V V _{IH} = 2.0 V	2		0.4	V
		② V _{IL} = 0.7 V ② V _{IL} = 0.8 V	1,3			
Input clamp voltage	V _{IC}	V _{CC} = 4.5 V, I _{IN} = -18 mA	1,2,3		-1.5	V
High level input current	I _{IH1}	V _{CC} = 5.5 V, V _{IN} = 2.7 V Unused inputs = 0.0 V	1,2,3		20	μA
	I _{IH2}	V _{CC} = 5.5 V, V _{IN} = 7.0 V Unused inputs = 0.0 V	1,2,3		0.1	mA
Low level input current	I _{IL}	V _{CC} = 5.5 V, V _{IN} = 0.4 V Unused inputs are ≥ 4.5 V	1,2,3		-0.2	mA
Output current	I _O	V _{CC} = 5.5 V, V _{OUT} = 2.25 V ③	1,2,3	-30	-112	mA
Supply current	I _{CCH}	V _{CC} = 5.5 V, V _{IN} ≥ 4.5 V	1,2,3		20	mA
	I _{CCL}	V _{CC} = 5.5 V, V _{IN} ≤ 0.4 V	1,2,3		29	
Functional tests		See 4.3.1c 4/	7,8			
Maximum clock frequency	f _{MAX}	V _{CC} = 4.5 V to 5.5 V C _L = 50 pF R _L = 500Ω 57 See figure 4	9,10,11	30		MHz
Propagation delay time, CLR to any Q	t _{PHL1}		9,10,11	4	21.5	ns
Propagation delay time, CLK to any Q	t _{PLH2}		9,10,11	2	16.5	ns
	t _{PHL2}			3	16.5	

1/ Unused inputs that do not directly control the pin under test must be put > 2.5 V or ≤ 0.4 V. The inputs shall not exceed 5.5 V or go less than 0.0 V. No inputs shall be floated.

2/ All outputs must be tested. In the case where only one input at V_{IL} maximum or V_{IH} minimum produces the proper output state, the test must be performed with each input being selected as the V_{IL} maximum or the V_{IH} minimum input.

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- 3/ The output conditions have been chosen to produce a current that closely approximates one half of the true short circuit output current, I_{OS} . Not more than one output will be tested at one time and the duration of the test condition shall not exceed 1 second.
- 4/ Functional tests shall be conducted at input test conditions of $GND \leq V_{IL} \leq V_{OL}$ and $V_{OH} \leq V_{IH} \leq V_{CC}$.
- 5/ Propagation delay limits are based on single output switching. Unused outputs = 3.5 V or ≤ 0.3 V.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*,2,3,7,8,9, 10,11
Group A test requirements (method 5005)	1,2,3,7,8,9, 10,11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

* PDA applies to subgroup 1.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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6.4 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5) has been submitted to DESC-ECS.

Military drawing part number	Vendor CAGE number	Vendor similar part number 1/
8413601RX	01295 27014	SNJ54ALS273J 54ALS273J/883
8413601SX	01295	SNJ54ALS273W
84136012X	01295 27014	SNJ54ALS273FK 54ALS273E/883

Caution: Do not use this number for item acquisition.
Items acquired to this number may not satisfy the
performance requirements of this drawing.

Vendor CAGE
number

01295

27014

Vendor name
and address

Texas Instruments, Incorporated
P.O. Box 6448
Midland, TX 79701

National Semiconductor
2900 Semiconductor Drive
Santa Clara, CA 95051

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